'H' Part number

Last Updated: May. 2012

DDR3 SDRAM PART NUMBERING

H 5 T Q XX X X X X X - XX X

1 2 3 4 5 6 7 8 9 10 11 12 13 14

HYNIX MEMORY

PRODUCT FAMILY

5 : DRAM

PRODUCT MODE

T : DDR3 SDRAM

POWER SUPPLY

Q : VDD=1.5V & VDDQ=1.5V
C : VDD=1.35V & VDDQ=1.35V
K : VDD=1.25V & VDDQ=1.25V

DENSITY & REFRESH

51 : 512Mb, 8K/64ms Refresh
1G : 1Gb, 8K/64ms Refresh
2G : 2Gb, 8K/64ms Refresh
4G : 4Gb, 8K/64ms Refresh
8G : 8Gb, 8K/64ms Refresh
AG : 16Gb, 8K/64ms Refresh

ORGANIZATION

4 : x4
8 : x8
6 : x16
2 : x32

NUMBER OF BANKS

3 : 8 Banks
4 : 16 Banks

DIE GENERATION

M : 1st
A : 2nd
B : 3rd
C : 4th
D : 5th
E : 6th
F : 7th
G : 8th

PACKAGE TYPE

F : FBGA SDP (Single Die Package)
L : FBGA DDP 1CS (Dual Die Package)
M : FBGA DDP 2CS (Dual Die Package)
H : FBGA QDP (Quad Die Package)

PACKAGE MATERIAL

L : Leaded
P : Lead Free (ROHS[4] compliant)
R : Lead Free & Halogen Free (ROHS[4] compliant)

SPEED(tCL-tRCD-tRP)

TE : DDR3-2133 14-14-14
RD : DDR3-1866 13-13-13
PB : DDR3-1600 11-11-11
H9 : DDR3-1333 9-9-9
G7 : DDR3-1066 7-7-7
S6 : DDR3-800 6-6-6

OPERATING TEMPERATURE & POWER CONSUMPTION

C : Commercial Temp[1] & Normal Power
L : Commercial Temp[1] & Low Power
E : Extended Temp[2] & Normal Power
I : Industrial Temp[3] & Normal Power
A : Commercial Temp[1] & 1.35 VDD Power
R : Commercial Temp[2] & 1.35 VDD Power & Reduced IDD6
U : Commercial Temp[2] & 1.25 VDD Power

Note:
1) Commercial Temperature: 0°C ~ 85°C
2) Extended Temperature: -25°C ~ 85°C
3) Industrial Temperature: -40°C ~ 85°C
4) ROHS : Restriction Of Hazardous Substances